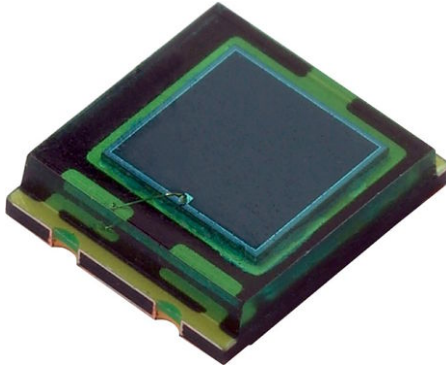




Ambient Light Sensor



DESCRIPTION

TEMD5510FX01 ambient light sensor is a PIN photodiode with high photo sensitivity in a miniature surface mount device (SMD). The detector chip has 7.5 mm² sensitive area. It is sensitive to visible light much like the human eye and has peak sensitivity at 540 nm.

FEATURES

- Package type: surface mount
- Package form: top view
- Dimensions (L x W x H in mm): 5 x 4.24 x 1.12
- Radiant sensitive area (in mm²): 7.5
- AEC-Q101 qualified
- High photo sensitivity
- Adapted to human eye responsivity
- Supression filter for near infrared radiation
- Angle of half sensitivity: $\phi = \pm 65^\circ$
- Floor life: 72 h, MSL 4, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Automotive sensors
- Ambient light sensors
- Backlight dimmers
- Notebooks
- Computers

PRODUCT SUMMARY			
COMPONENT	I _{ra} (μA)	φ (deg)	λ _{0.5} (nm)
TEMD5510FX01	1	± 65	430 to 610

Note

- Test conditions see table “Basic Characteristics”

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TEMD5510FX01	Tape and reel	MOQ: 1500 pcs, 1500 pcs/reel	Top view

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	16	V
Power dissipation	T _{amb} ≤ 25 °C	P _V	215	mW
Junction temperature		T _j	100	°C
Operating temperature range		T _{amb}	-40 to +100	°C
Storage temperature range		T _{stg}	-40 to +110	°C
Soldering temperature	Acc. reflow solder profile fig. 5	T _{sd}	260	°C
Thermal resistance junction/ambient	Soldered on PCB with pad dimensions: 4 mm x 4 mm	R _{thJA}	350	K/W

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Breakdown voltage	$I_R = 100\text{ }\mu\text{A}$, $E = 0$	$V_{(BR)}$	16			V
Reverse dark current	$V_R = 10\text{ V}$, $E = 0$	I_{ro}		2	30	nA
Diode capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D		1600		pF
	$V_R = 3\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D		730		pF
Reverse light current	$E_e = 1\text{ mW/cm}^2$, $\lambda = 550\text{ nm}$, $V_R = 5\text{ V}$	I_{ra}		26		μA
	$E_v = 100\text{ lx}$, CIE illuminant A, $V_R = 5\text{ V}$	I_{ra}	0.8	1	1.4	μA
Temperature coefficient of I_{ra}	$E_v = 100\text{ lx}$, CIE illuminant A, $V_R = 5\text{ V}$	$TK_{I_{ra}}$		0.2		%/K
Angle of half sensitivity		ϕ		± 65		deg
Wavelength of peak sensitivity		λ_p		540		nm
Range of spectral bandwidth		$\lambda_{0.5}$		430 to 610		nm

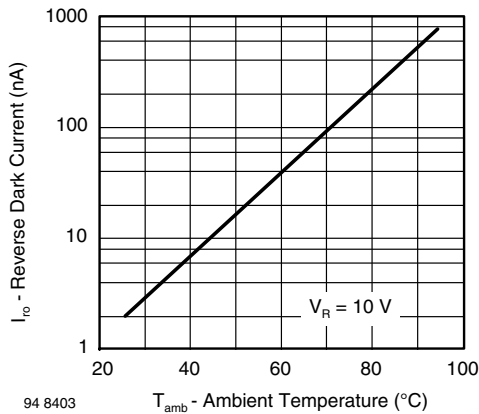
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

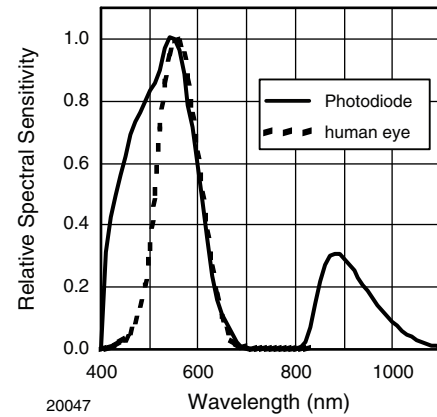


Fig. 3 - Relative Spectral Sensitivity vs. Wavelength

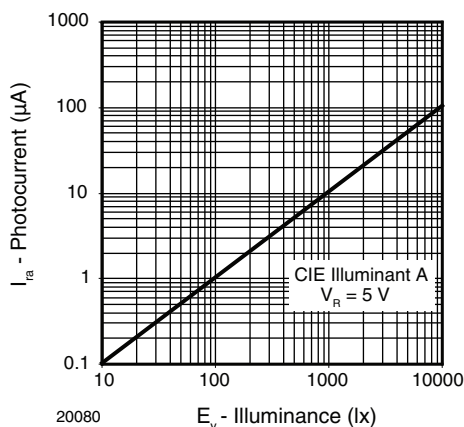


Fig. 2 - Reverse Light Current vs. Irradiance

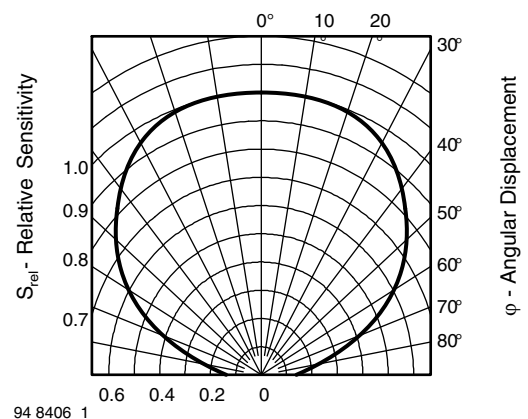
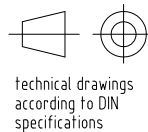
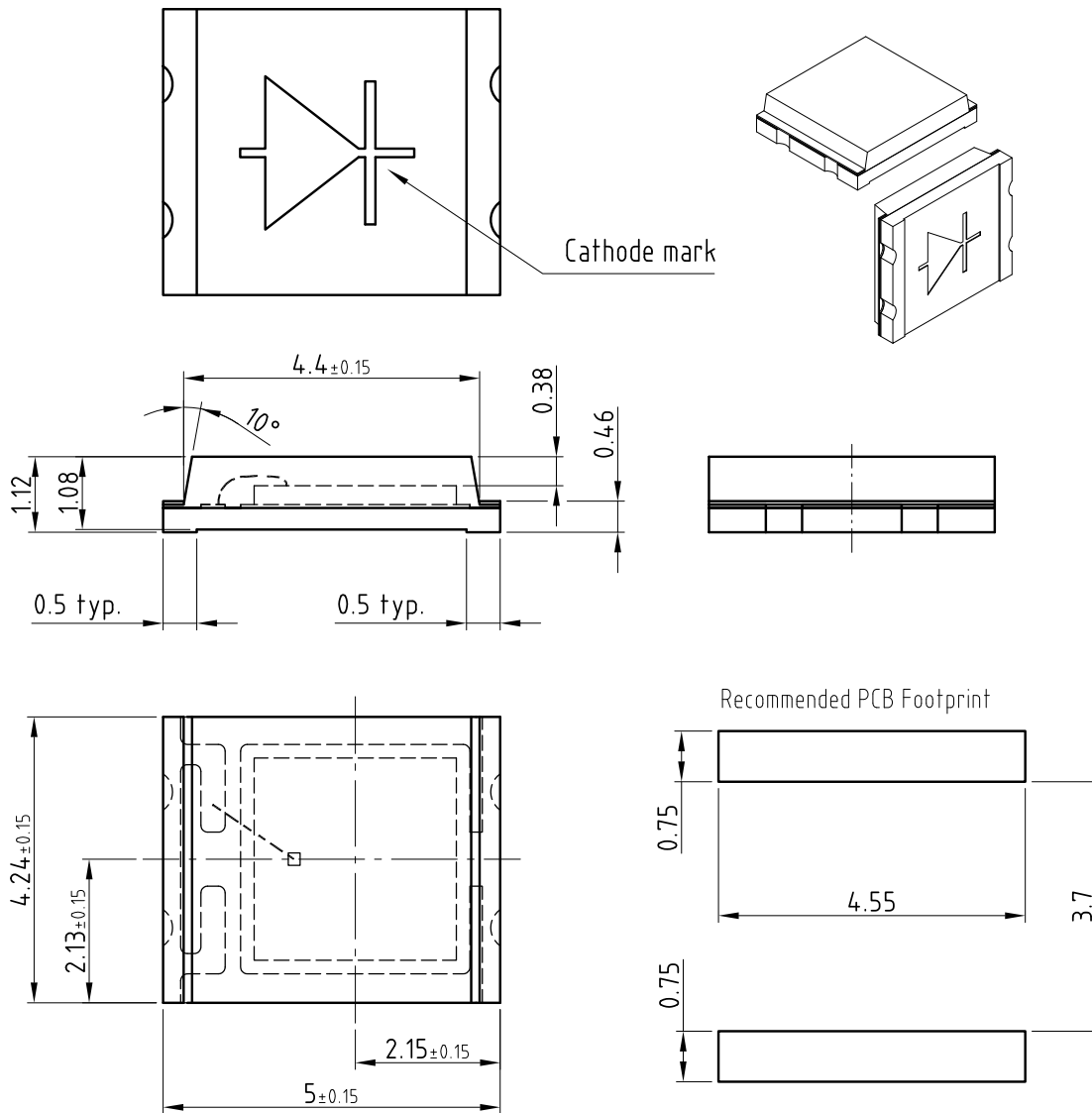


Fig. 4 - Relative Radiant Sensitivity vs. Angular Displacement



PACKAGE DIMENSIONS in millimeters

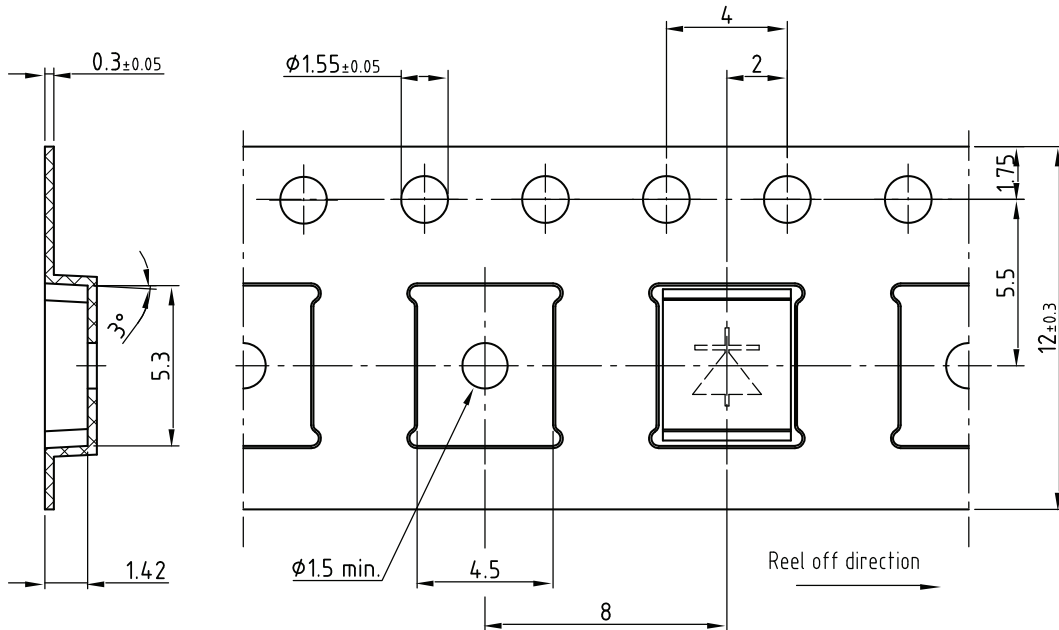


technical drawings according to DIN specifications

Drawing-No.: 6.541-5060.01-4
Issue: 3; 05.02.08
20536

Not indicated tolerances ± 0.1

TAPING DIMENSIONS in millimeters

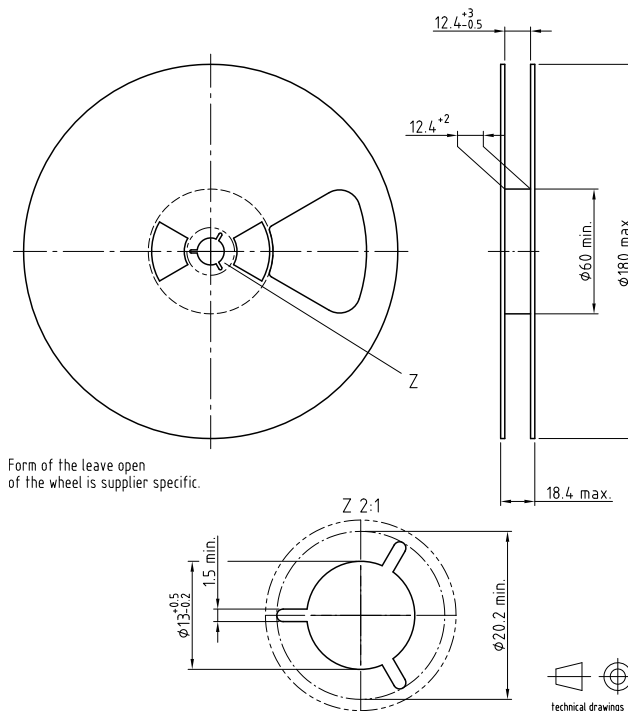


Drawing-No.: 9.700-5293.01-4
 Issue: 1; 03.12.04
 20537

Not indicated tolerances ± 0.1

technical drawings according to DIN specifications

REEL DIMENSIONS in millimeters



Form of the leave open of the wheel is supplier specific.

Drawing-No.: 9.800-5097.01-4
 Issue: 1; 05.05.08
 20874

technical drawings according to DIN specifications



SOLDER PROFILE

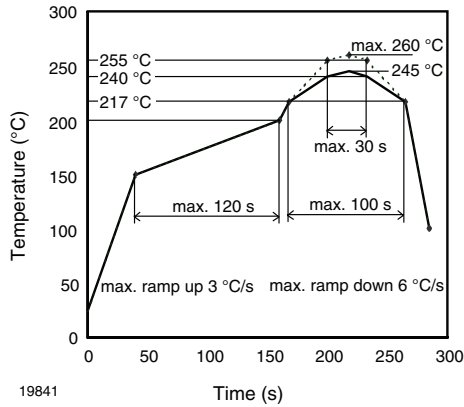


Fig. 5 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 4

Floor life: 72 h

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at 40 °C (+ 5 °C), $RH < 5\%$

or

96 h at 60 °C (+ 5 °C), $RH < 5\%$.



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